

# METHOD AND APPARATUS FOR REDUCING COMPRESSED DRY AIR USAGE DURING CHEMICAL MECHANICAL PLANARIZATION

## ABSTRACT OF THE DISCLOSURE

A chemical mechanical planarization (CMP) system is provided. The system includes a polishing surface and a platen disposed along an underside of the polishing surface. A retaining ring surrounds the platen. The retaining ring includes a lower annular sleeve and an upper annular sleeve moveably disposed over the lower annular sleeve. A method for reducing a consumption of compressed dry air (CDA) during a chemical mechanical planarization (CMP) operation is also described.